

INTEGRATED CIRCUIT HEATING SYSTEM AND METHOD THEREFOR

Related Patent Documents

on
ppm
9/23/04
5 This application is related to and fully incorporates U.S. Patent Application
Serial No. 09/585921 (AMDA.478PA), entitled "Internal Heating System and
Method Therefor," and filed concurrently herewith.

Field of the Invention

10 The present invention relates generally to semiconductor analysis and, more
particularly, to semiconductor analysis involving temperature control of a
semiconductor die.

Background of the Invention

15 The electronics industry continues to rely upon advances in semiconductor
technology, including integrated circuits (ICs), to realize higher-functioning devices in
more compact areas. For many applications, realizing higher-functioning devices
requires integrating a large number of electronic devices into a single silicon die. In
addition, many of the individual devices within the die are being manufactured with
smaller physical dimensions. As the number of electronic devices per given area of the
20 silicon die increases, and as the size of the individual devices decreases, testing
processes become more important and more difficult.

Many integrated circuit dice include circuits having random defects. These
defects can recover or fail under particular operating conditions and at higher